IBIS Open Forum Minutes

Meeting Date: October 9, 2009

VOTING MEMBERS AND 2009 PARTICIPANTS

Actel (Prabhu Mohan)

Agilent Brian Andresen, Radek Biernacki, Saliou Dieye,

Yutao Hu, Fangyi Rao

AMD Nam Nguyen
Ansoft Corporation Steve Pytel
Apple Computer (Matt Herndon)
Applied Simulation Technology
ARM V. Muniswara Reddy

Cadence Design Systems Terry Jernberg*, Ambrish Varma

Cisco Systems Luis Boluna, Tram Bui, Bill Chen, Syed Huq*,

Mike LaBonte*, Pedo Miran, Huyen Pham,

AbdulRahman (Abbey) Rafiq, Ashwin Vasudevan,

Zhiping Yang

Ericsson Anders Ekholm*
Green Streak Programs Lynne Green
Hitachi ULSI Systems (Kazuyoshi Shoji)
IBM Adge Hawes

Infineon Technologies AG (Christian Sporrer)

Intel Corporation Myoung J. Choi, Michael Mirmak*, Vishram Pandit, Jon

Powell, Sirisha Prayaga

IO Methodology Li (Kathy) Chen, Lance Wang*, Zhi (Benny) Yan

LSI Brian Burdick*

Mentor Graphics Weston Beal, Vladimir Dmitriev-Zdorov, Zhen Mu,

Arpad Muranyi*

Micron Technology Randy Wolff*
Nokia Siemens Networks GmbH Eckhard Lenski*
Samtec (Corey Kimble)

Signal Integrity Software Barry Katz, Walter Katz*, Todd Westerhoff

Sigrity Brad Brim, Sam Chitwood

Synopsys Ted Mido
Teraspeed Consulting Group Bob Ross*

Toshiba (Yasumasa Kondo)
Xilinx [David Banas]
ZTE (Ying Xiong)

Zuken Michael Schaeder, Ralf Bruening

OTHER PARTICIPANTS IN 2009

AET Mikio Kiyono

Altera Hui Fu Apache Yu Lin ATE Nob Tanak, Kenny Suga Bayside Design Stephen Coe, Elliot Nahas

Circuit Spectrum Zaven Tashjian

CST Antonio Ciccomancini, Martin Schauem

Curtiss-Wright Embedded J. Phillips

Computing

EM Integrity Guy de Burgh Exar Helen Nguyen

Freescale Jon Burnett, Om Mandhama

Huawei Technologies Xiaoqing Dong, Chunxing Huang, Guan Tao

ICT Solutions Steven Wong

IdemWorks Michelangelo Bandinu

Juniper Kevin Ko

Kineret Design Ricardo Teliuteuesh Leventhal Design & Roy Leventhal

Communications

Maxim Integrated ProductsRon OlisarMindspeed TechnologiesBobby AlkayNetLogic MicrosystemsEric HsuPolitecnico di TorinoIgor Stievano

Sanmina SCI Vladimir Drivanenko

Sedona International Joe Socha Siemens Manfred Maurer

Signal Consulting Group Timothy Coyle, Nicole Mitchell

Simberian Yuriy Shlepnev
TechAmerica (GEIA) (Chris Denham)
Texas Instruments Pavani Jella
Xsigo Systems Robert Badel
Independent Ian Dodd

In the list above, attendees at the meeting are indicated by *. Principal members or other active members who have not attended are in parentheses. Participants who no longer are in the organization are in square brackets.

UPCOMING MEETINGS

The bridge numbers for future IBIS teleconferences are as follows:

Date Meeting Number Meeting Password

October 30, 2009 204 387 881 IBIS

For teleconference dial-in information, use the password at the following website: https://cisco.webex.com/cisco/j.php?J=204387881

All teleconference meetings are 8:00 AM to 9:55 AM US Pacific Time. Meeting agendas are typically distributed seven days before each Open Forum. Minutes are typically distributed

within seven days of the corresponding meeting. When calling into the meeting, press 3 to attend the meeting, then follow the prompts to enter the meeting ID. For new, local international dial-in numbers, please reference the bridge numbers provided by Cisco Systems at the following link:

http://www.cisco.com/web/about/doing business/conferencing/index.html

NOTE: "AR" = Action Required.

INTRODUCTIONS AND MEETING QUORUM

No new participants.

CALL FOR PATENTS

Bob Ross called for any patents or pending patents related to the IBIS 3.2, IBIS 4.2, IBIS 5.0 or ICM 1.1 specifications. No patents were declared.

MEMBERSHIP UPDATE AND TREASURER'S REPORT

Bob Ross reported that we have 29 paid members. He is waiting for confirmation from TechAmerica on payments of one or two additional memberships.

REVIEW OF MINUTES AND ARS

Bob Ross called for comments regarding the minutes of the September 18, 2009 IBIS Open Forum teleconference. The minutes were approved without any changes.

WEB PAGE UPDATES

Syed Huq reported that there were no web page updates this time. He noted that Bob sent him a few minor changes to make yesterday, so he will be making those changes shortly. Bob Ross noted that there was a web outage. Several people noticed and reported it. There was a renewal issue with the eigroup.org domain, and it took a few days to get restored.

MAILING LIST ADMINISTRATION

Mike LaBonte reported that there were a few drops and additions on the mailing list. Everything is working normally.

MODEL LIBRARY UPDATE

Anders Ekholm reported that he has updated all the links, and he sent the updated page to TechAmerica. The new page has not been published yet.

PRESS UPDATE

None.

MISCELLANY/ANNOUNCEMENTS

None.

OPENS FOR NEW ISSUES

Bob Ross added 'DesignCon Planning' as a separate item from the 'Other Events' planning.

INTERNATIONAL/EXTERNAL ACTIVITIES

- DASC

Michael Mirmak reported that the next meeting is October 15. The DASC file and e-mail archive may be found at:

http://www.dasc.org/

- P1735 Encryption

Syed Huq reported that the October 5 meeting was cancelled. The next meeting is October 19. He noted that several more companies have joined the encryption forum. The IEEE Study Group on Encryption web reflector archives are found at:

http://www.eda-stds.org/ip-encrypt/hm/

-Conferences

The Electrical Performance of Electronic Packaging and Systems (EPEPS 2009) is October 19-21, 2009 at the Embassy Suites in Portland, OR. This is a major meeting for SI people from universities and industry.

http://www.epep.org/

The 7th International Workshop on Electromagnetic Compatibility of Integrated Circuits (EMC COMPO 2009) is November 17-20, 2009 in Toulouse, France.

http://www.emccompo.org

TECHAMERICA STATUS

No update.

IEC APPROVAL ACTIVITIES

Randy Wolff reported that the IEC meeting was September 28-30, 2009. He has not heard any update from Victor Berman, so he will email him to find out the status of IEC approval of the IBIS 4.2 specification.

SUMMIT STATUS

-China Summit Planning

The meeting is scheduled for Wednesday, November 4 at the Four Points Hotel in Shanghai in the Pudong district. Bob Ross reported that another announcement will go out next week. IO Methodology has been added as a co-sponsor. Funds have been transferred into Lance Wang's account for paying meeting expenses. 12 presentations are scheduled. The formal agenda will go out one week before the meeting. Vendor tables need to be arranged. Co-sponsors include Huawei Technologies, Agilent Technologies, Ansoft, Cadence Design, Cybernet Systems, Intel, IO Methodology, Mentor Graphics, SiSoft, Sigrity, Synopsys and ZTE Corporation.

-Japan Summit Planning

The meeting is scheduled for Friday, November 6 at the JEITA headquarters from 2:00 PM to 6:00 PM. Bob Ross noted that there have been several signups already. There will be a full program. Vendor tables will be arranged by JEITA. Co-sponsors include Japan Electronics and Information Technology Industries Association (JEITA), ATE (Sigrity Distributor), Cadence, Zuken and others to be determined.

-DesignCon Planning

Bob Ross sent a contract agreement between IBIS and IEC to officers for review. We need to decide what day to hold the meeting. The most likely choice is Thursday, February 4, 2010. Monday is the second choice, but this is the day for tutorials. Bob is working with Syed Huq to make sure we have a backup meeting room with the hotel in case we can't get a room in the convention center. Bob questioned whether we want an IBIS booth. The booth is complimentary, but there are a lot of extra fees.

-Other Events

None.

Sponsorship opportunities for all upcoming IBIS summits are available, with sponsors receiving free mentions in the minutes, agenda, and other announcements. Contact the IBIS Board for further details.

IBIS QUALITY TASK GROUP

Mike LaBonte reported that the group finished reviewing changes to the Quality specification suggested by Randy Wolff and others. He posted an updated version. This included a new check 5.2.14, "[Receiver Thresholds]: Threshold_sensitivity and Ext_ref present and match datasheet, if needed." Bob Ross noted that there are a couple of presentations related to model quality at the China summit.

The Quality Task Group checklist and other documentation can be found at:

http://www.eda-stds.org/ibis/quality_wip/

IBIS MODEL REVIEW TASK GROUP

No update.

ADVANCED TECHNOLOGY MODELING TASK GROUP

Arpad Muranyi reported that the group has discussed a better flow diagram for AMI for the IBIS 5.1 specification. They are making progress on this, but he asked for more comments. Next week, there will be a presentation from Vladimir Dmitriev-Zdorov on a proposal for how to make waveforms in the new flow more accurate. The group also needs to squeeze in time to finalize the IBIS ISS documentation.

Task group material can be found at:

http://www.eda-stds.org/ibis/macromodel_wip/

AD HOC TASK GROUPS (INTERCONNECT)

Michael Mirmak reported that the group meets Wednesdays at 9 AM PT. They are discussing sparse matrix keywords. IBM brought up support for binary file formats, noting a format they use. The group will discuss possible support for this.

Task group material can be found at:

http://www.eda.org/ibis/adhoc/interconnect/

TOUCHSTONE TSCHK2 PARSER LICENSE

Bob Ross noted that at the last meeting, a price of \$1000 was proposed for a tschk2 parser license. The current parser is being developed for free, but Bob noted that we can't assume future development will be free, so we need to bring in some funds for this. Anders Ekholm asked about how to handle payments made for the parser. Bob said he would ask companies to make payments for next year, so we will not lose the funding at the end of the fiscal year. Bob motioned to set a fee of \$1000 for a tschk2 parser license. Michael Mirmak seconded the motion. The vote passed with the following vote tally:

Cadence yes Cisco yes Ericsson yes Intel yes IO Methodology yes LSI yes Mentor yes Micron yes Nokia yes SiSoft ves Teraspeed yes

NEW ISSUES

None.

IBIS QUALITY SPECIFICATION VERSION 2.0 REVIEW

Bob Ross asked for any comments. The document was updated with recent changes after the last Quality Committee meeting. Mike LaBonte discussed Check 5.2.1 that relates to the Vinl and Vinh values found under [Model]. The original wording noted that DC values should be used. This came from an example found in the IBIS specification, even though the description of these parameters makes no mention of use of AC or DC values. Mike changed the text in the Quality specification to remove mention of DC, so the user can choose whether to use AC or DC values for Vinl and Vinh parameters. It is suggested to use values related to the values used in [Model Spec]. Randy Wolff noted that he liked the change, as it allows the user to decide what is most appropriate to use. Randy asked if a BIRD should be written to change the example in the IBIS specification. Bob suggested he write up a BIRD for review. Mike noted that many models include Vinl and Vinh values that have no relation to AC or DC values. He thinks the values should have some useful meaning for tools that don't support [Model Spec] or [Receiver Thresholds]. The document will be voted on October 30.

The document can be downloaded from:

http://www.eda-stds.org/ibis/quality_wip/iq_ver_2_0.pdf

IBISCHK5 PARSER STATUS

Michael Mirmak reported that last minute delays are keeping the parser from being released. Compiled versions for Windows and Sun OS are complete, but SuSE Enterprise Server 9 (Linux) is having issues. The parser developer has been notified and is making changes. Michael will send Mike LaBonte the code to try compiling on his Linux system.

TSCHK2 PARSER STATUS

Michael Mirmak reported that he is continuing to get questions from the developer. The code development is on schedule. Questions have helped to make light of areas of the specification needing clarity.

IBISCHK4 BUG STATUS

Bob Ross noted that there are no new BUGs to report.

The BUG report list is available at the link below:

http://www.eda.org/ibis/bugs/ibischk/

ICMCHK1 BUG STATUS

All BUGs have been closed. No new BUGs have been filed.

NEW ISSUES

Bob Ross noted that he will be introducing a new term, TSIRD, as a label for changes related to the Touchstone 2.0 document.

NEXT MEETING

The next IBIS Open Forum teleconference will be held October 30, 2009 from 8:00 to 10:00 AM US Pacific Standard Time.

NOTES

IBIS CHAIR: Bob Ross (503) 246-8048, Fax: (503) 239-4400

bob@teraspeed.com

Staff Scientist, Teraspeed Consulting Group

10238 SW Lancaster Road

Portland, OR 97219

VICE CHAIR: Lance Wang (978) 633-3388

lwang@iometh.com

President / CEO, IO Methodology, Inc.

PO Box 2099

Acton, MA 01720

SECRETARY: Randy Wolff (208) 363-1764, Fax: (208) 368-3475

rrwolff@micron.com

SI Modeling Manager, Micron Technology, Inc.

8000 S. Federal Way Mail Stop: 01-711 Boise, ID 83707-0006

LIBRARIAN: Anders Ekholm (46) 10 714 27 58, Fax: (46) 8 757 23 40

ibis-librarian@eda.org

Digital Modules Design, PDU Base Stations, Ericsson AB

BU Network Färögatan 6

164 80 Stockholm, Sweden

WEBMASTER: Syed Huq (408) 525-3399, Fax: (408) 526-5504

huqs@cisco.com

Manager, Hardware Engineering, Cisco Systems

170 West Tasman Drive

San Jose, CA 95134-1706

POSTMASTER: Mike LaBonte (978) 936-2147

milabont@cisco.com

Signal Integrity Engineer, Cisco Systems Mail Stop BXB01/1/ 1414 Massachusetts Ave Boxborough, MA 01719

This meeting was conducted in accordance with the GEIA Legal Guides and GEIA Manual of Organization and Procedure.

The following e-mail addresses are used:

majordomo@eda.org

In the body, for the IBIS Open Forum Reflector: subscribe ibis <your e-mail address>

In the body, for the IBIS Users' Group Reflector: subscribe ibis-users <your e-mail address>

Help and other commands: help

ibis-request@eda.org

To join, change, or drop from either or both: IBIS Open Forum Reflector (ibis@eda.org) IBIS Users' Group Reflector (ibis-users@eda.org) State your request.

ibis-info@eda.org

To obtain general information about IBIS, to ask specific questions for individual response, and to inquire about joining the EIA-IBIS Open Forum as a full Member.

ibis@eda.org

To send a message to the general IBIS Open Forum Reflector. This is used mostly for IBIS Standardization business and future IBIS technical enhancements. Job posting information is not permitted.

ibis-users@eda.org

To send a message to the IBIS Users' Group Reflector. This is used mostly for IBIS clarification, current modeling issues, and general user concerns. Job posting information is not permitted.

ibis-bug@eda.org

To report ibischk parser BUGs. The BUG Report Form resides along with reported BUGs at:

http://www.eda.org/ibis/bugs/ibischk/ http://www.eda.org/ibis/bugs/ibischk/bugform.txt

icm-bug@eda.org

To report icmchk1 parser BUGs. The BUG Report Form resides along with reported BUGs at:

http://www.eda.org/ibis/icm_bugs/
http://www.eda.org/ibis/icm_bugs/icm_bugform.txt

To report s2ibis, s2ibis2 and s2iplt bugs, use the Bug Report Forms which reside at:

http://www.eda.org/ibis/bugs/s2ibis/bugs2i.txt http://www.eda.org/ibis/bugs/s2ibis2/bugs2i2.txt http://www.eda.org/ibis/bugs/s2iplt/bugsplt.txt

Information on IBIS technical contents, IBIS participants and actual IBIS models are available on the IBIS Home page:

http://www.eigroup.org/ibis/ibis.htm

Check the IBIS file directory on eda.org for more information on previous discussions and results:

http://www.eda.org/ibis/directory.html

Other trademarks, brands and names are the property of their respective owners.

IBIS CURRENT MEMBER VOTING STATUS

I/O Buffer Information Specification Committee (IBIS)

		Standards Ballot				
	Interest	Voting	August 7,	August 28,	September	October 9
Organization	Category	Status	2009	2009	18, 2009	2009
Actel	Producer	Inactive				
Advanced Micro Devices	Producer	Inactive		\checkmark		
Agilent Technologies	User	Inactive				
Ansoft	User	Inactive				
Apple Computer	User	Inactive				
Applied Simulation Technology	User	Inactive				
ARM	Producer	Inactive				
Cadence Design Systems	User	Inactive		√		√
Cisco Systems	User	Active	√	√	√	√
Ericsson	Producer	Active	√	√	√	√
Green Streak Programs	General Interest	Inactive				
Hitachi ULSI Systems	Producer	Inactive				
IBM	Producer	Inactive	√			
Infineon Technologies AG	Producer	Inactive				
Intel Corp.	Producer	Active		√	√	√
IO Methodology	User	Active	√	√	√	√
LSI	Producer	Active	√		√	√
Mentor Graphics	User	Active	√	√	√	√
Micron Technology	Producer	Active	√	√	√	√
Nokia Siemens Networks	Producer	Active	√	√	√	√
Samtec	Producer	Inactive				
Signal Integrity Software	User	Active	√	√	√	√
Sigrity	User	Inactive				
Synopsys	User	Inactive				
Teraspeed Consulting	General Interest	Active	√	√	√	√
Toshiba	Producer	Inactive				
Xilinx	Producer	Inactive				
ZTE	User	Inactive				
Zuken	User	Inactive				

CRITERIA FOR MEMBER IN GOOD STANDING:

- MUST ATTEND TWO CONSECUTIVE MEETINGS TO ESTABLISH VOTING MEMBERSHIP
- MEMBERSHIP DUES CURRENT
- MUST NOT MISS TWO CONSECUTIVE MEETINGS

INTEREST CATEGORIES ASSOCIATED WITH GEIA BALLOT VOTING ARE:

- USERS MEMBERS THAT UTILIZE ELECTRONIC EQUIPMENT TO PROVIDE SERVICES TO AN END USER.
- PRODUCERS MEMBERS THAT SUPPLY ELECTRONIC EQUIPMENT.
- GENERAL INTEREST MEMBERS ARE NEITHER PRODUCERS NOR USERS. THIS CATEGORY INCLUDES, BUT IS NOT LIMITED TO,
 GOVERNMENT, REGULATORY AGENCIES (STATE AND FEDERAL), RESEARCHERS, OTHER ORGANIZATIONS AND ASSOCIATIONS,
 AND/OR CONSUMERS.